



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

Jung-Chih HU et al.

Confirmation No.: 5769

Serial No.: 10/070,000

Examiner: Edna Wong

Filed: November 27, 2002

Group Art Unit: 1753

Title: ELECTROPLATING SOLUTION FOR COPPER ELECTROPLATING

**SUBMISSION OF FORMAL DRAWINGS**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Please substitute the attached thirty-two (32) formal drawings for the informal drawings filed in the above-identified application.

No fee is believed to be due in association with this filing, however, the Commissioner is hereby authorized to charge fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required to facilitate this filing, or credit any overpayment to Deposit Account No. 13-3402.

Respectfully submitted,

James E. Ruland, Reg. No. 37,432  
Attorney for Applicants

MILLEN, WHITE, ZELANO &  
BRANIGAN, P.C.  
Arlington Courthouse Plaza 1, Suite 1400  
2200 Clarendon Boulevard  
Arlington, Virginia 22201  
Telephone: (703) 243-6333  
Facsimile: (703) 243-6410

**CERTIFICATION OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Services as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on: **February 9, 2004**

Name: Sharon McDaniel

Signature: *Sharon McDaniel*  
MILLEN, WHITE, ZELANO & BRANIGAN, P.C.

Attorney Docket No.: MERCK-2395

Date: February 9, 2004